

## PMP40269 Test Results

### 1. Efficiency

Test at board end

Vin(V)	Iin(mA)	B_VBUS(V)	Io1(A)	A_VBUS(V)	Io2(A)	Effi.(%)
7.01	0.580	5.093	0.480	5.108	0.295	97.2
6.99	1.185	5.117	0.957	5.135	0.596	96.0
7.00	1.812	5.138	1.434	5.160	0.899	94.7
7.00	2.456	5.155	1.913	5.183	1.190	93.2
6.97	3.173	5.163	2.400	5.195	1.491	91.1

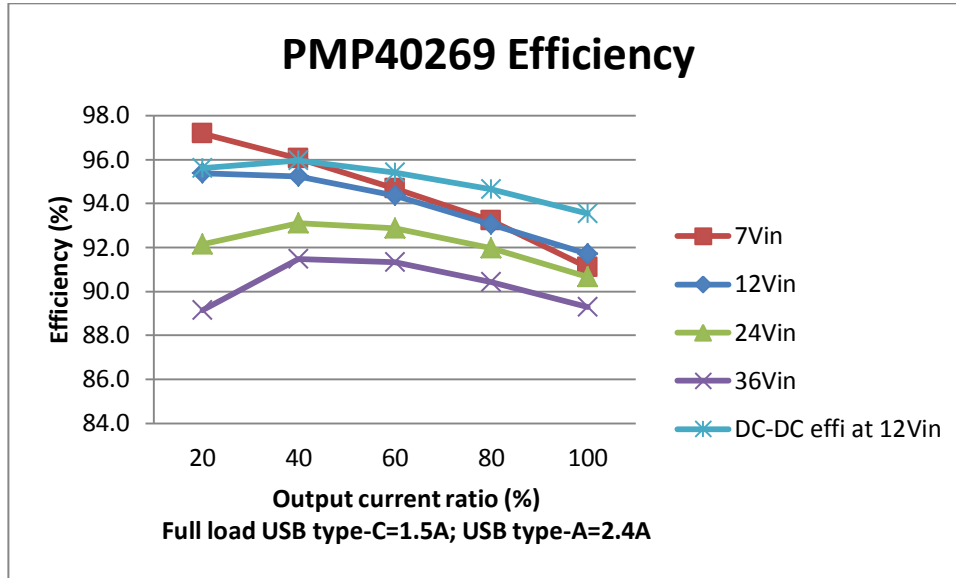
Vin(V)	Iin(mA)	B_VBUS(V)	Io1(A)	A_VBUS(V)	Io2(A)	Effi.(%)
11.99	0.346	5.095	0.480	5.110	0.295	95.4
12.04	0.694	5.118	0.957	5.135	0.596	95.2
11.97	1.063	5.138	1.434	5.160	0.899	94.3
11.91	1.457	5.158	1.923	5.183	1.201	93.0
12.00	1.833	5.173	2.400	5.205	1.491	91.7

Vin(V)	Iin(mA)	B_VBUS(V)	Io1(A)	A_VBUS(V)	Io2(A)	Effi.(%)
23.96	0.179	5.095	0.480	5.108	0.295	92.1
23.93	0.357	5.115	0.956	5.133	0.596	93.1
23.99	0.539	5.138	1.434	5.160	0.899	92.9
23.98	0.727	5.155	1.913	5.180	1.190	92.0
23.98	0.928	5.170	2.400	5.203	1.491	90.7

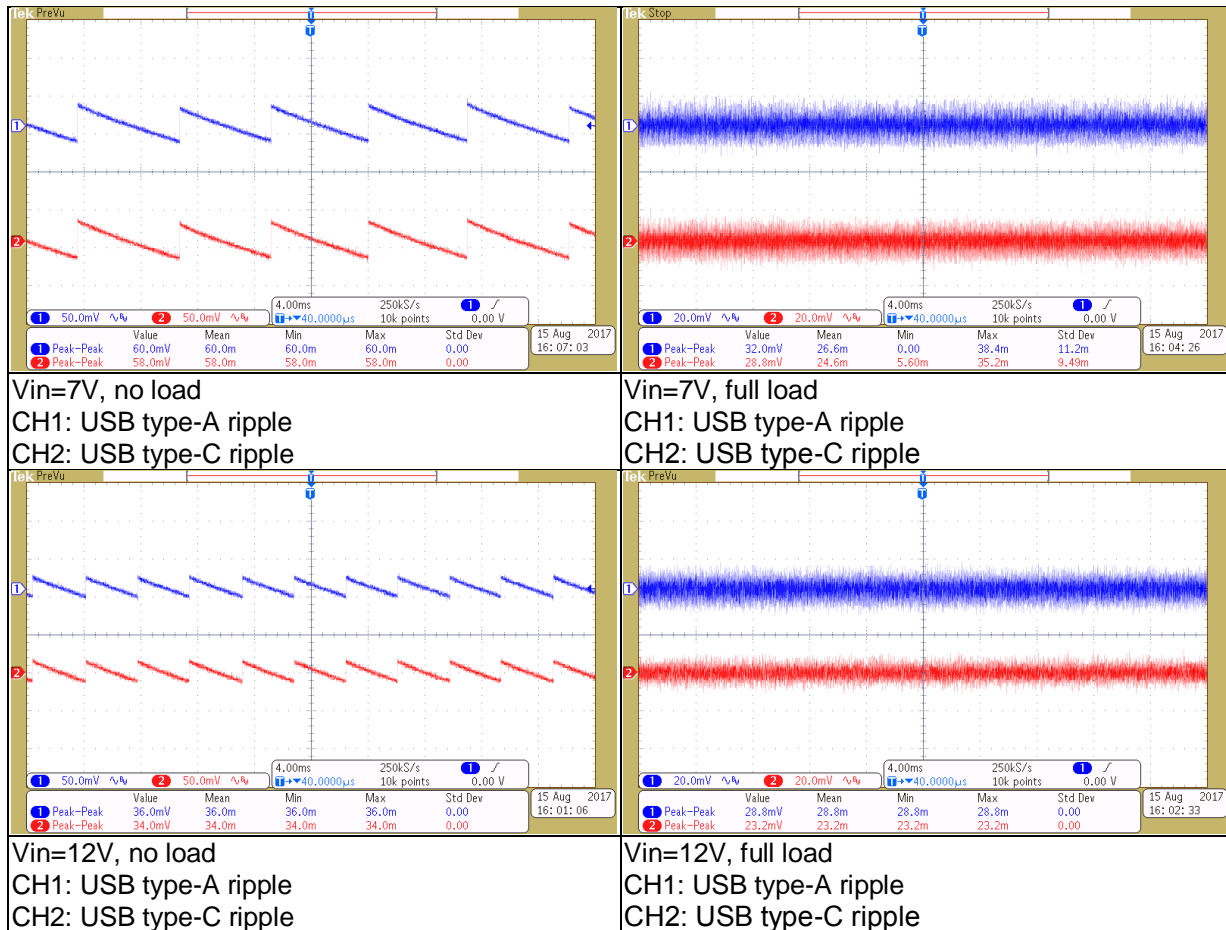
Vin(V)	Iin(mA)	B_VBUS(V)	Io1(A)	A_VBUS(V)	Io2(A)	Effi.(%)
36.04	0.123	5.095	0.480	5.108	0.295	89.2
36.02	0.242	5.116	0.958	5.135	0.598	91.5
36.00	0.365	5.138	1.434	5.158	0.899	91.3
35.97	0.493	5.155	1.913	5.180	1.189	90.4
35.94	0.628	5.168	2.400	5.200	1.493	89.3

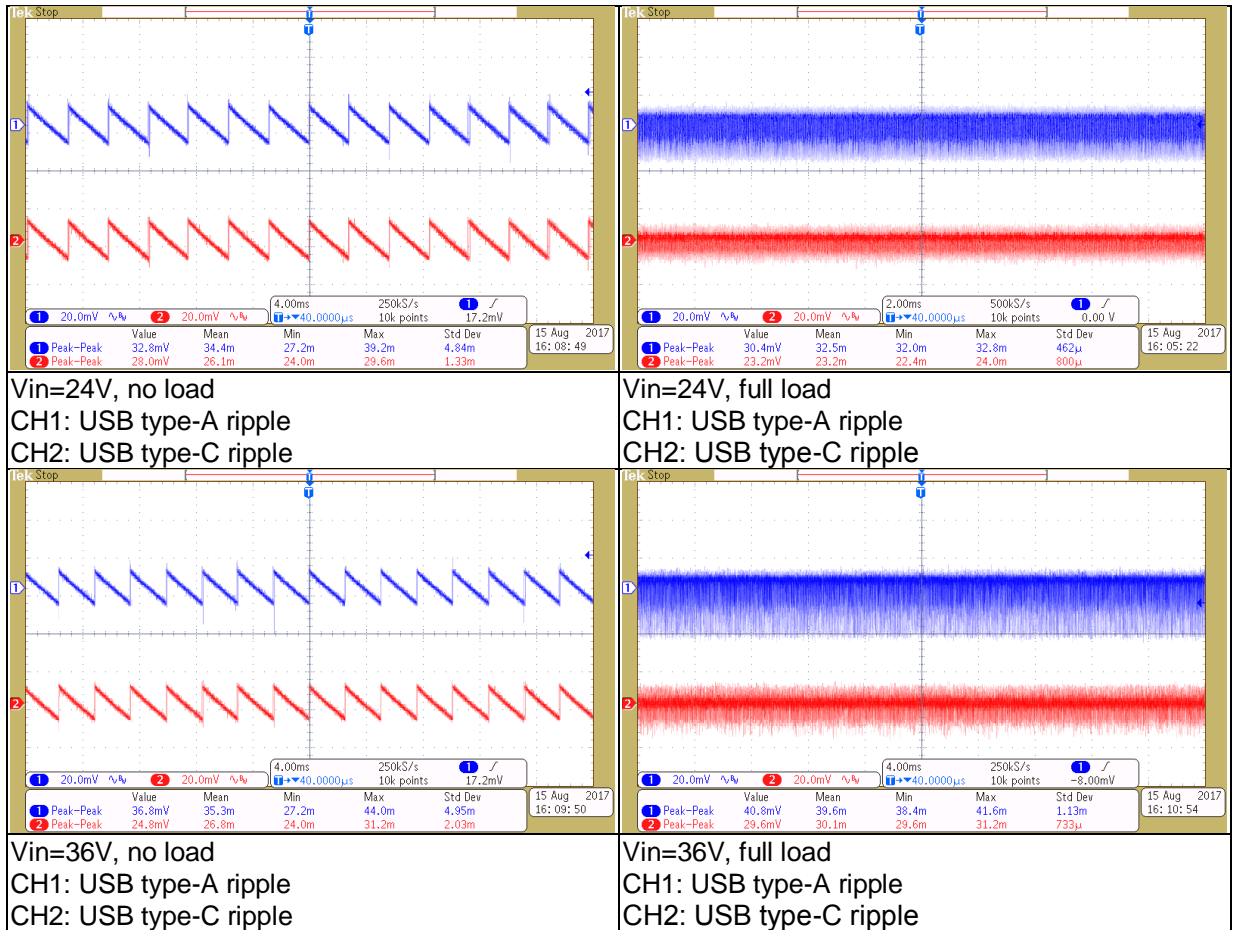
DC/DC efficiency

Vin(V)	Iin(mA)	Vo(V)	Io(A)	Effi.(%)
12.02	0.345	5.083	0.780	95.6
11.95	0.690	5.083	1.556	96.0
11.95	1.040	5.080	2.333	95.4
11.96	1.395	5.078	3.110	94.6
11.98	1.763	5.073	3.896	93.6

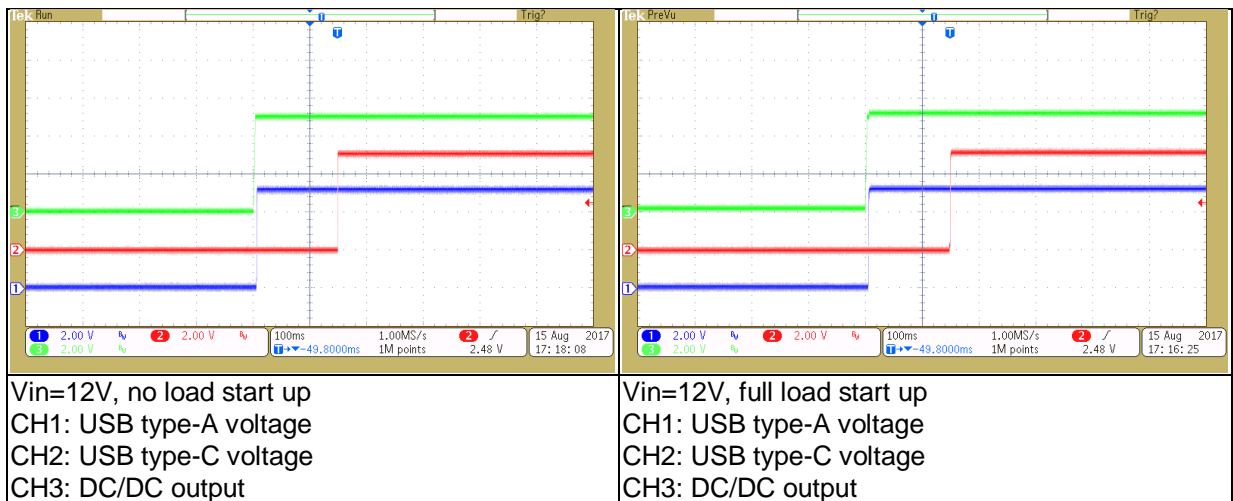


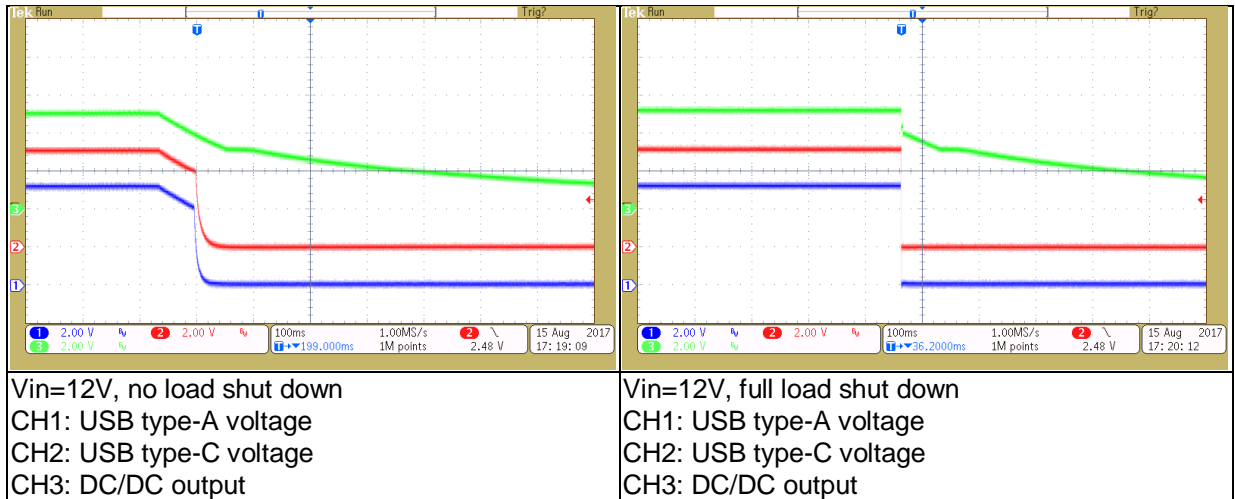
## 2. Ripple and noise



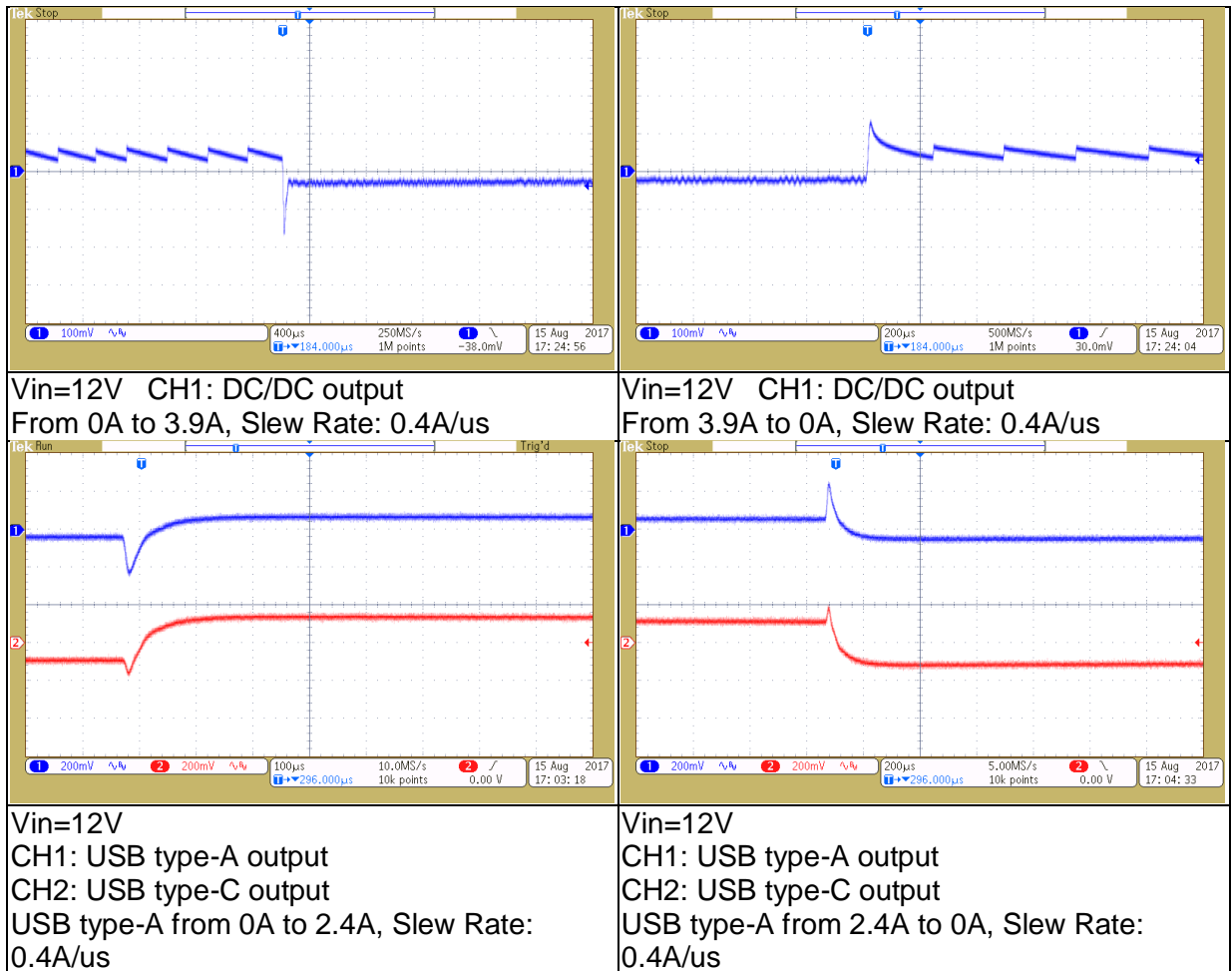


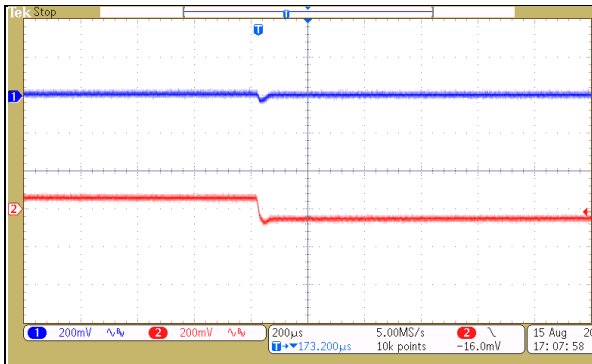
### 3. Start up and Shut down



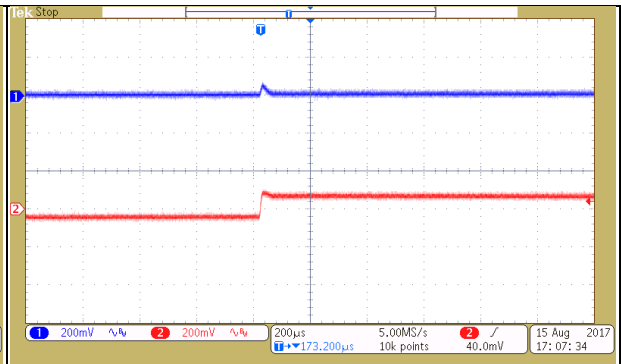


#### 4. Load Transient



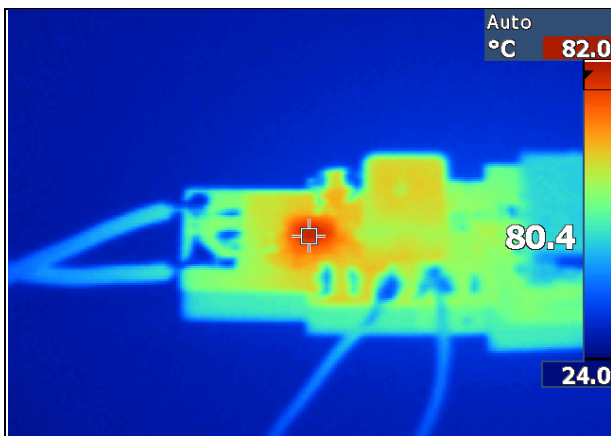


Vin=12V  
 CH1: USB type-A output  
 CH2: USB type-C output  
 USB type-C from 0A to 1.5A, Slew Rate:  
 0.4A/us



Vin=12V  
 CH1: USB type-A output  
 CH2: USB type-C output  
 USB type-C from 1.5A to 0A, Slew Rate:  
 0.4A/us

## 5. Thermal



Vin=12V  
 USB type-C=1.5A; USB type-A=2.4A

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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